

1. STANDARD APPEARANCE

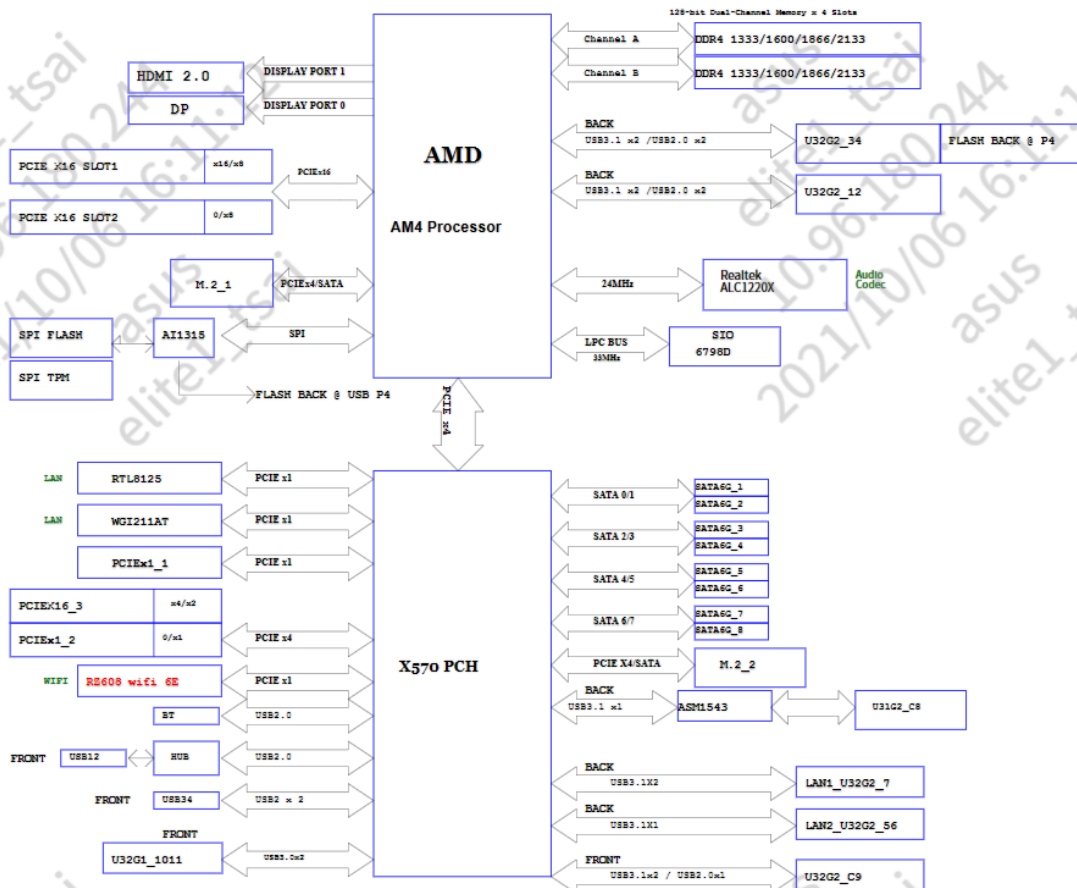


2. BLOCK DIAGRAM

ROG STRIX X570-E GAMING WIFI II

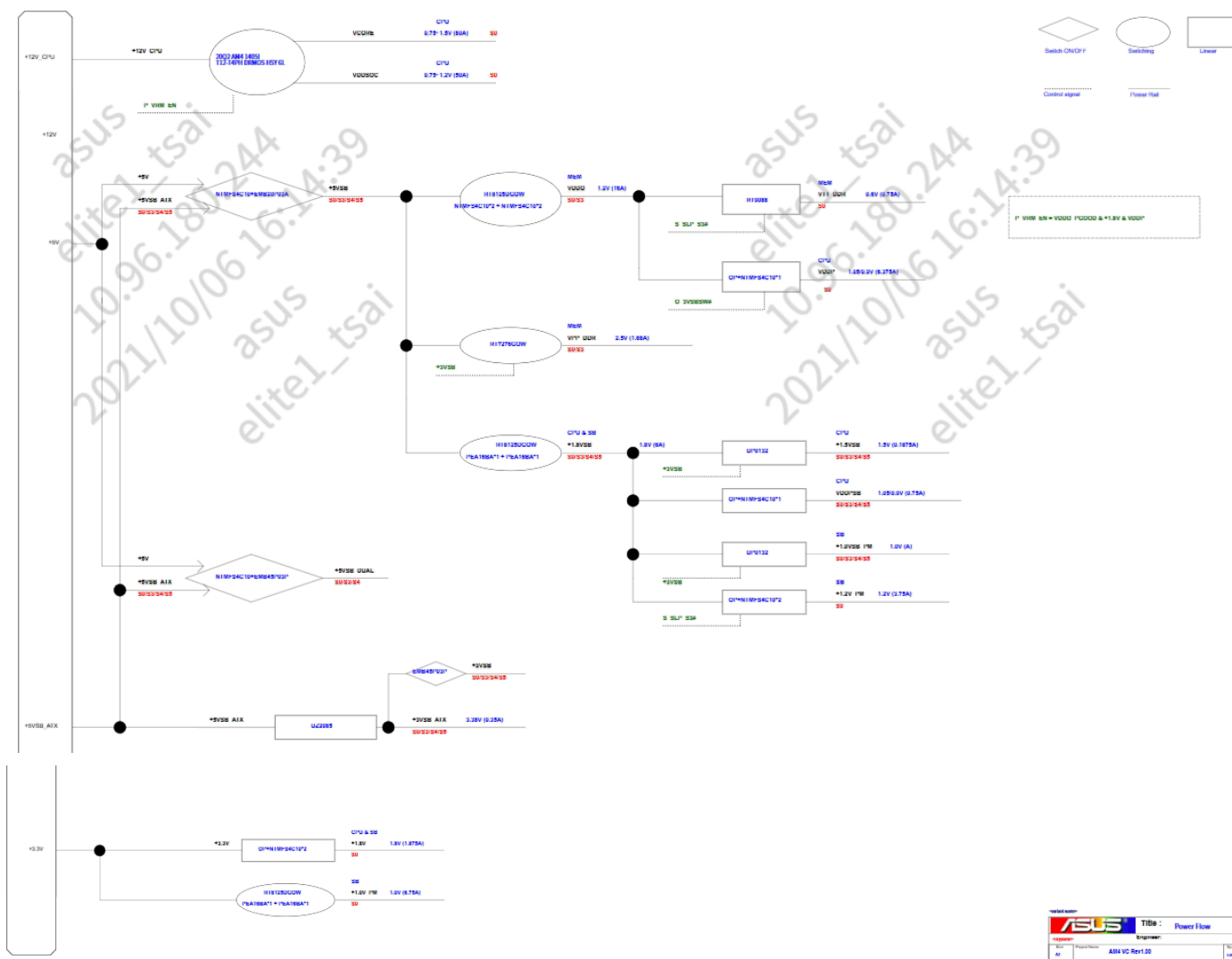
Rev 1.01X

20210729

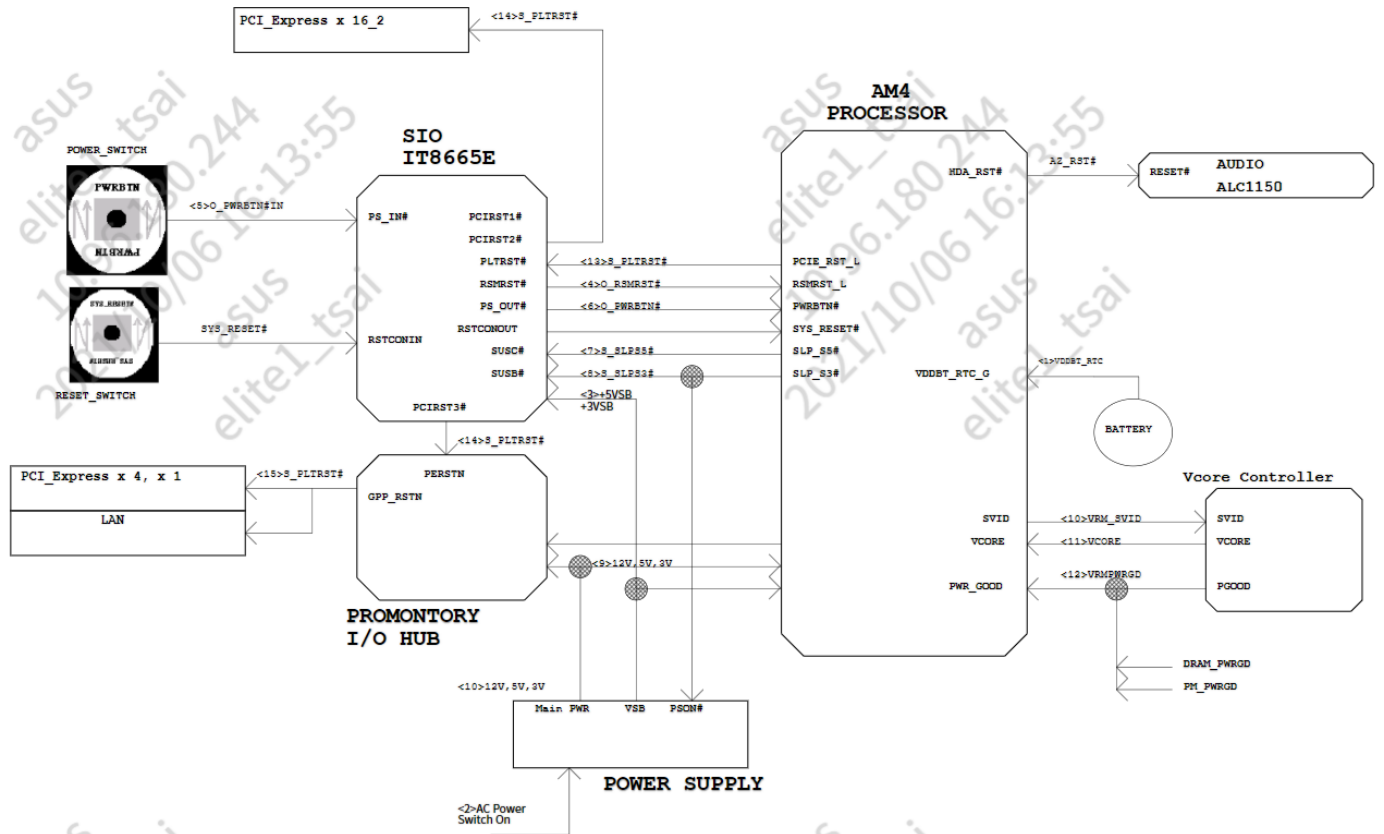


ASUS		Title : Block Diagram	
ASUS Computer Inc.		Engineer: Elaihetz_U	
Size	Project Name	AM4	Rev
A3			01.00
Date: Thursday, July 29, 2021		Printed	1 of 128

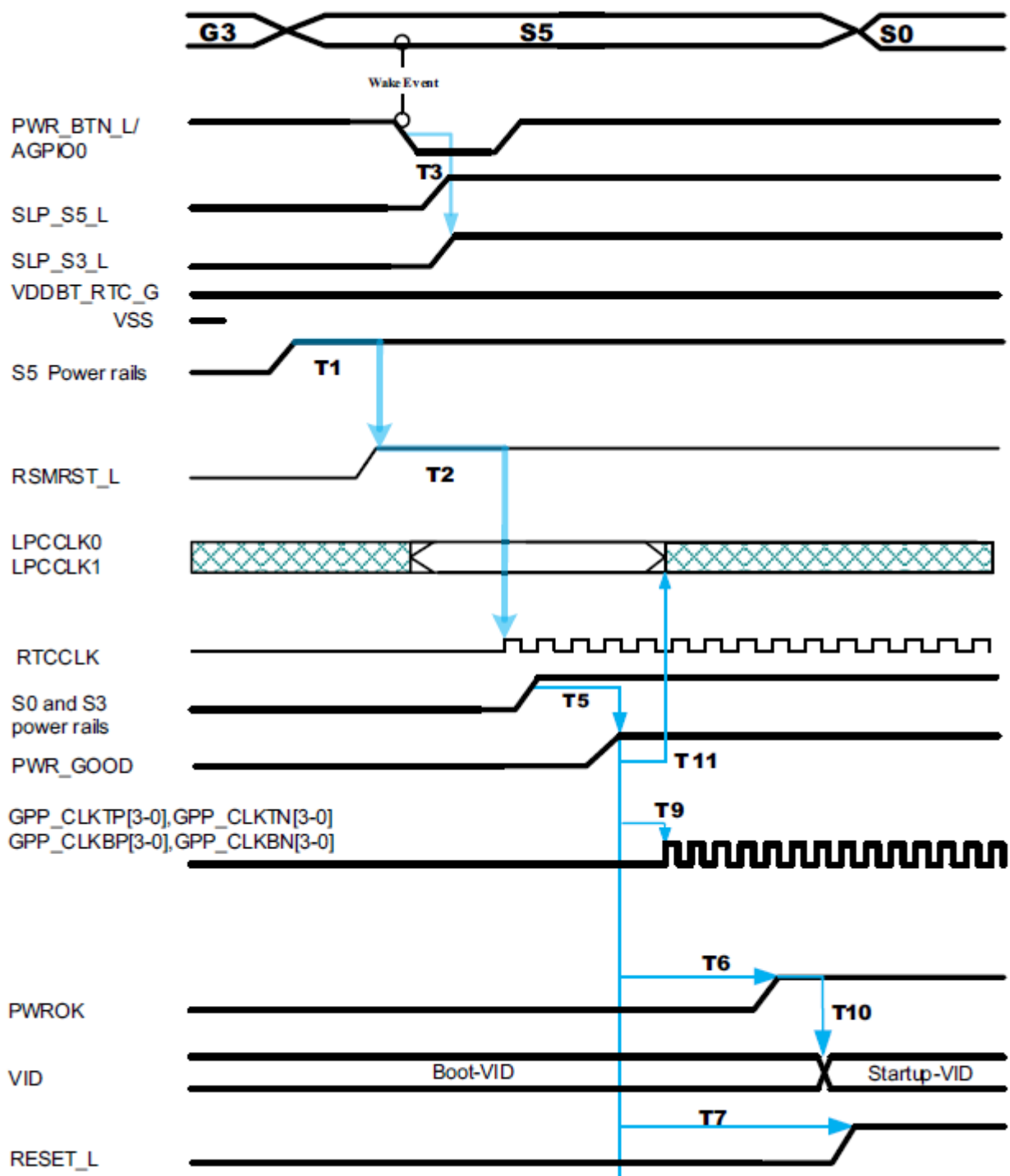
3. POWER FLOW



4. POWER ON SEQUENCE

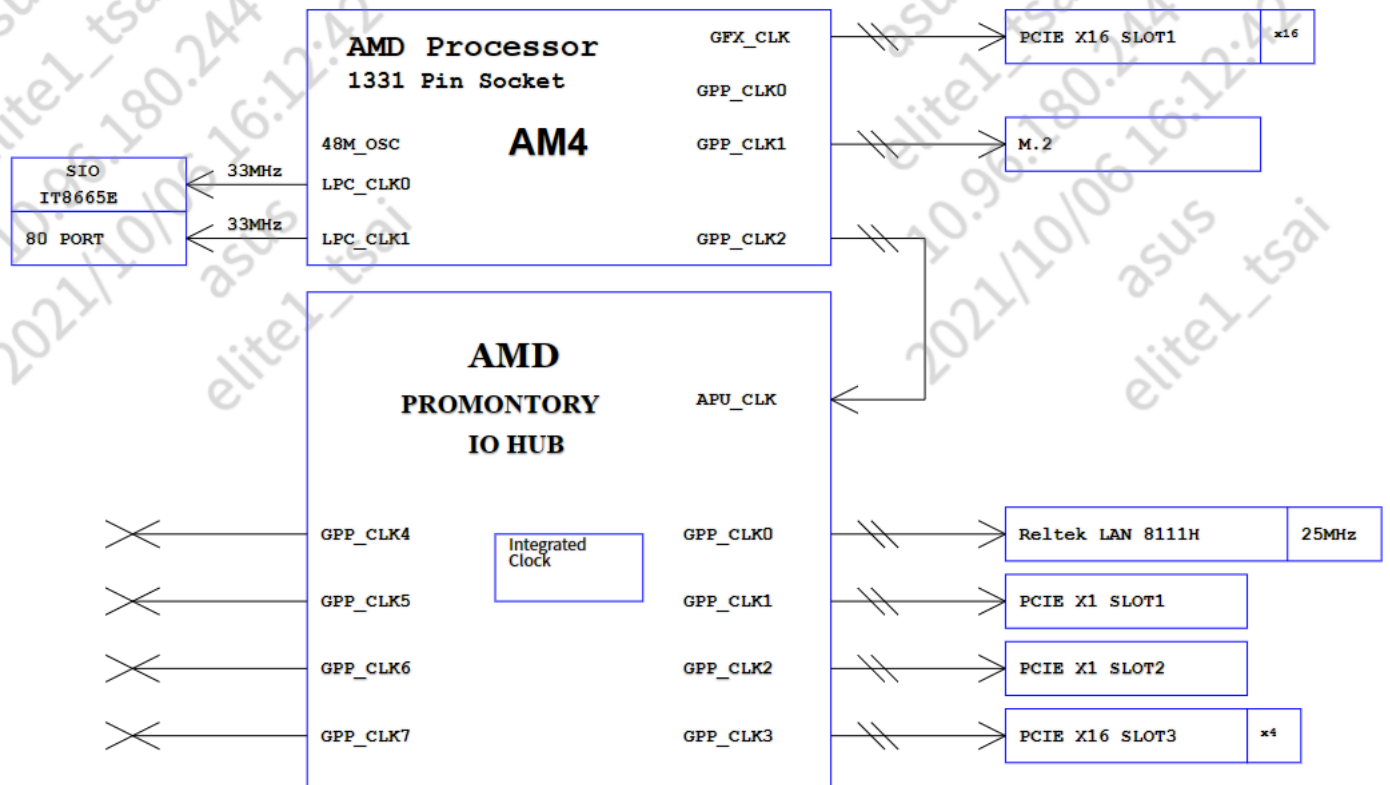


5. Timing Diagram for G3 to S0

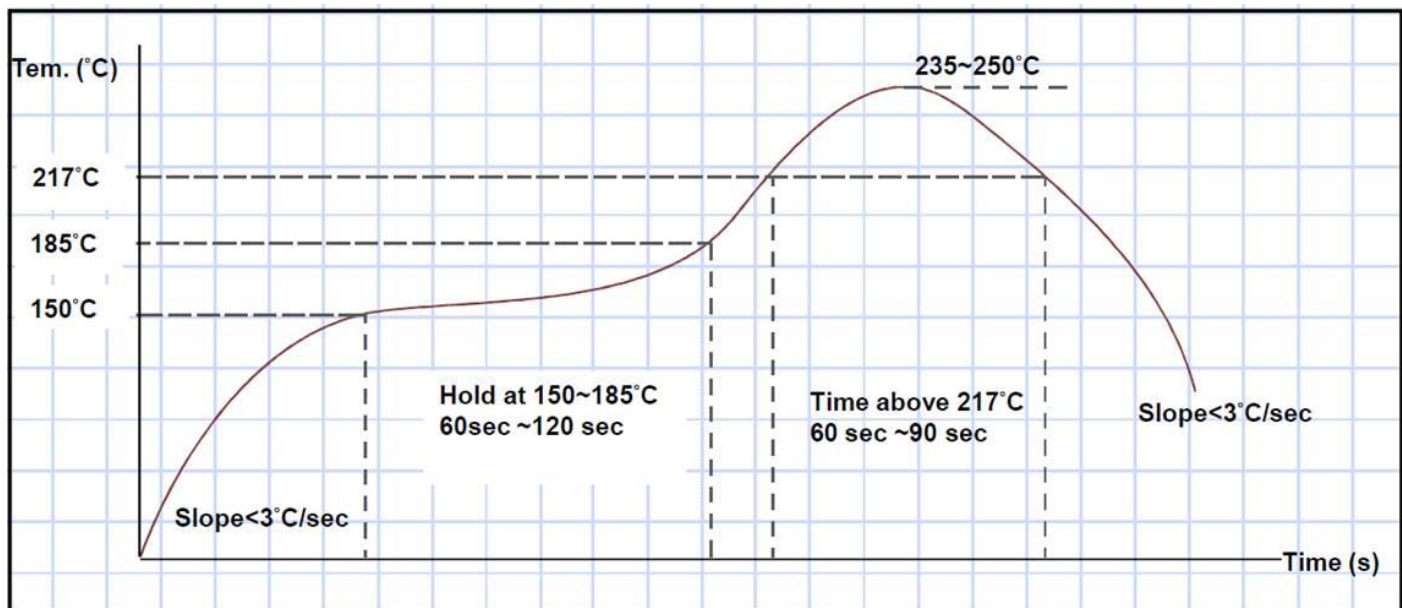


6. Frequency Flow

ICG : Integrated Clock Gen.



7. Socket reflow profile



Profile Feature	SMT Component Vendor Spec
Preheat/Soak	150 °C
Temperature Min (T _{min})	200 °C
Temperature Max (T _{max})	need endure 120 seconds
Time (ts) from (T _{min} to T _{max})	
Ramp-up rate (TL to Tp)	need endure 3 °C/second max.
Liquidous temperature (TL)	217 °C
Time (tL) maintained above TL	need endure 90 seconds
Peak package body temperature (Tp)	260 °C
Time (tp)* within 5 °C of the specified classification temperature (Tc), see Figure 1-1 .	need endure 10* seconds
Ramp-down rate (Tp to TL)	need endure 6 °C/second max.
Time 25 °C to peak temperature	need endure 8 minutes max.

Note 1: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow (e.g., live-bug). If parts are reflowed in other than the normal live-bug assembly reflow orientation (i.e., dead-bug), Tp shall be within $\pm 2^{\circ}C$ of the live-bug Tp and still meet the Tc requirements, otherwise, the profile shall be adjusted to achieve the latter. To accurately measure actual peak package body temperatures refer to JEP140 for recommended thermocouple use.

Note 2 : For SMT type component, it need be able to withstand twice times SMT Reflow + once DIP Wave soldering process.